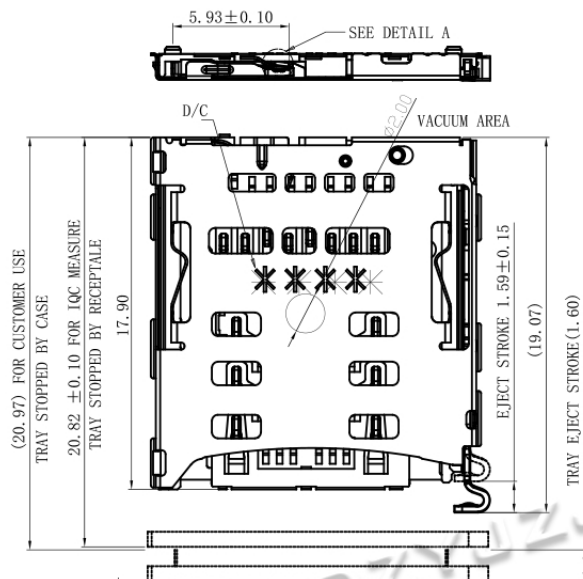
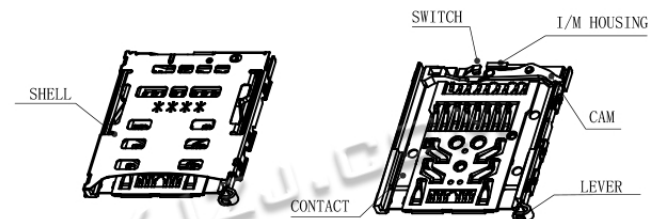
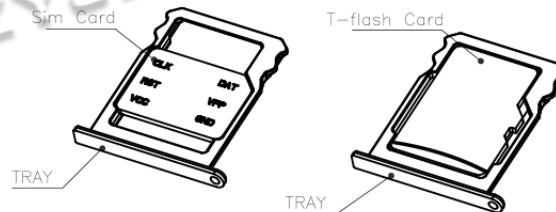
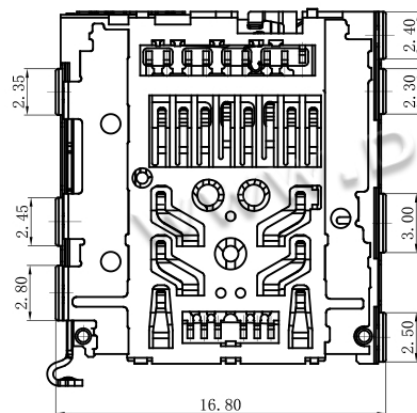
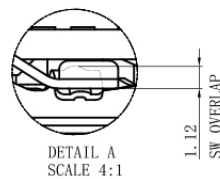


(SOLDER TAIL)
 0.08 BEFORE IR
 0.10 AFTER IR



NOTES:

1. FINISH

1-1. CONTACT:

CONTACT AREA: Au 15u' Min.; SW AREA: Au 5u' Min;
 GOLD PLATING ON SOLDER AREA, 3u' Min.

1-2. SHELL:

SW AREA: 3u' Min.; SOLDER AREA: Au 3u' Min.

2. ELECTRICAL REQUIREMENTS:

2-1. CURRENT RATING: 1A PER PIN.

2-2. CONTACT RESISTANCE: 60 mOhm MAX.

2-3. INSULATION RESISTANCE: 1000 Mohm MIN. 200 VDC FOR 1 MINUTE.

2-4. WITHSTANDING STRENGTH: 500V AC FOR 1 MINUTE.

3. MECHANICAL REQUIREMENTS:

3-1. TRAY MATING FORCE: 1.0kgf MAX.; TRAY UNMATING FORCE: 0.4kgf MIN.

3-2. DURABILITY: 3,000 CYCLES MIN.

4. ENVIRONMENT REQUIREMENTS:

4-1. OPERATING TEMP.: -30° C TO +85° C

4-2. STORAGE TEMPERATURE: -40° C TO +85° C

5. UNLESS OTHERWISE SPECIFIED, ALL DIMENSIONS ARE IN mm.

5	CAM	1	SUS304-H	NO PLATING
4	LEVER	1	SUS301-H	NO PLATING
3	SHELL	1	SUS301-H	Plating Ni 10~50u' over all SWITCH AREA: Au 3u' min. SOLDER AREA: Au 3u' min.
2	I/M HOUSING	1	LCP	BLACK COLOR, UL94 V-0
1	CONTACT	1	Copper Alloy	Plating Ni 30~200u' over all CONTACT AREA: Au 15u' min. SWITCH AREA: Au 5u' min. SOLDER AREA: Au 3u' min.
ITEM	PART NAME	Q' TY	MATERIAL	FINISH



深圳市华宇创精密电子有限公司

TOLERANCE:
 X.X ±0.30
 X.XX ±0.25
 X.XXX ±0.15
 X' ±2" X.X' ±0.5"

UNIT: mm [inch]
 SCALE: 1:1 SIZE: A4

DRAWN BY :

陈一鸣

DATE :

2014-02-23

PART NAME:

NANO SIM+TF 1.4H 二选一卡座

CHECKED BY:

马跃

DATE :

2014-02-23

PART NO.

HYC60-2IN122-140

MOLD NO.

APPROVED BY:

邱敏

DATE :

2014-02-23

DRAW NO:

HYC-2401161410

SHEET NO.

1 OF 1

